Yeping Wang

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Education

University of Wisconsin-Madison, Madison, WI Ph.D. in Computer Sciences

Research Advisor: Prof. Michael Gleicher

Johns Hopkins University, Baltimore, MD

M.S.E. in Robotics

August 2018 - May 2020

GPA: 3.97/4.0

August 2020 - present

GPA: 3.93/4.0

Research Advisor: Prof. Chien-Ming Huang

South China University of Technology, Guangzhou, China September 2014–June 2018 B.E. in Mechanical Engineering GPA: 3.88/4.0

Publications

Peer-Reviewed Conference Papers

- 5. Wang, Y., Praveena, P., Rakita, D., Gleicher, M. (2023). RangedIK: An Optimization-Based Robot Motion Generation Method for Ranged-Goal Tasks. 2023 IEEE International Conference on Robotics and Automation (ICRA'23). Acceptance Rate 43%
- 4. Wang, Y., Sifferman C., Gleicher, M. (2023). Exploiting Task Tolerances in Mimicry-based Telemanipulation. 2023 IEEE/RSJ International Conference on Intelligent Robots and Systems (IROS'23). Acceptance Rate 43%
- 3. Praveena, P., Wang, Y., Mutlu, B., Gleicher, M. (2023). Periscope: A Robotic Camera System to Support Remote Physical Collaboration. 2023 ACM SIGCHI Conference on Computer-Supported Cooperative Work & Social Computing (CSCW'23).
- 2. Praveena, P., Molina, L., **Wang, Y.**, Senft, E., Mutlu, B., Gleicher, M. (2022). Understanding Control Frames in Multi-Camera Robot Telemanipulation. 2022 ACM/IEEE International Conference on Human-Robot Interaction (HRI'22). Acceptance Rate 25%
- 1. Wang, Y., Ajaykumar, G., and Huang, C.-M. (2020). See What I See: Enabling User-Centric Robotic Assistance Using First-Person Demonstrations. 2020 ACM/IEEE International Conference on Human-Robot Interaction (HRI'20). Acceptance Rate 24%

Peer-Reviewed Journal Articless

- 2. Sifferman C., Wang, Y., Gupta, M. and Gleicher, M. (2023). Unlocking the Performance of Proximity Sensors by Utilizing Transient Histograms. *IEEE Robotics and Automation Letters*
- 1. Rupal, B.*, Mostafa, K.*, Wang, Y.*, and Qureshi, A.J. (2019). A Reverse CAD Approach for Estimating Geometric and Mechanical Behavior of FDM Printed Parts. *Procedia Manufacturing*, 34, 535-544. *Equal Contribution

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Experiences

Teaching Assistant August 2020–May 2021 CS559 Computer Graphics & CS400 Programming III, UW–Madison Madison, WI

Course Assistant January-May 2019 CS 482/682 Deep Learning, JHU Baltimore, MD

Research Intern May-July 2018 China National Engineering Research Center for Healthcare Devices Guangzhou, China

Summer Research Intern June-September 2016 University of Alberta Edmonton, Canada

Mentor: Prof. Ahmed Qureshi

Honors and Awards

| CS Departmental Summer RA-ship, University of Wisconsin-Madison | 2021 |
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| CS Departmental Scholarship, University of Wisconsin-Madison | 2020 |
| Annual 10 Merit Students, South China University of Technology | 2017 |
| China National Scholarship, Ministry of Education of the P.R. China | 2016 |
| China National Scholarship, Ministry of Education of the P.R. China | 2015 |

Technical Skills

Programming C++, Python, Rust, JavaScript, MATLAB, HTML, CSS, LATEX

Frameworks/Libraries ROS, MoveIt!, PyTorch, OpenCV, ACADO, Git, Docker, THREE.js, D3.js

Software Adobe Illustrator, SolidWorks, ANSYS, AutoCAD, and Inventor

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